

L Number	Hits	Search Text	DB	Time stamp
1	2	"6683369"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:06
2	4	"2003017654"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:07
3	2	"20030017654"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:43
4	17775	second adj area	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:43
5	30381	second adj region	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:44
6	1705364	substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:44
7	4119	resin adj support	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:45
8	7	(second adj region) and substrate and (resin adj support)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:46
9	5003	support adj pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:47
10	13405	BGA	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:47
11	165035	support adj member	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:48
12	560	(second adj region) and (support adj member)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:48

13	56	((second adj region) and (support adj member)) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:49
14	1362019	semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:49
15	20	((second adj region) and (support adj member)) and package) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 11:00
16	0	resin adj dummy adj bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 11:00
17	167	dummy adj bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 11:01
18	113	semiconductor and (dummy adj bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 11:02
19	47488	(second adj area) (second adj region)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 11:02
20	2	(semiconductor and (dummy adj bump)) and ((second adj area) (second adj region))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 11:07
21	37	(dummy adj bump) and resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 11:09
22	122	resin adj bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 11:09
23	89	semiconductor and (resin adj bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 11:19
24	2	(semiconductor and (resin adj bump)) and dummy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 11:57

25	0	plastic adj dummy adj bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 11:58
26	2	(dummy adj bump) near resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 12:11
27	114	resin adj support adj member	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 12:12
28	16	semiconductor and (resin adj support adj member)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 12:14
29	60	epoxy adj spacer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 12:15
30	2	epoxy adj dummy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 12:15
31	8	(epoxy adj spacer) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 12:22
32	122	resin adj bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 12:22
33	12	plastic adj bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 12:22
34	37	epoxy adj bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 12:23
35	30	semiconductor and (epoxy adj bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 12:29
36	18	dummy adj plastic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 13:17

37	631	resin adj spacer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 13:18
38	68	semiconductor and (resin adj spacer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 13:19
39	11	(semiconductor and (resin adj spacer)) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 13:20
40	1	BGA and (resin adj spacer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 14:08
41	6	"6208022"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 14:10
42	14744	flexible adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 14:11
43	7	(dummy adj bump) and (flexible adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 14:50
44	68	support adj bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 14:51
45	39	(support adj bump) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 15:34
46	60308	supporting adj member	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 15:35
47	172	(supporting adj member) and (flexible adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 15:46
48	478	supporting adj spacer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 15:47

49	1	(supporting adj spacer) and (flexible adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 15:48
50	0	(supporting adj spacer) and semiconductor and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 15:49
51	25	(supporting adj spacer) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 16:00
52	9	"5635756"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 16:01